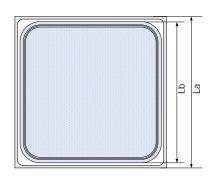


### 2SB267100MA LOW IR SCHOTTKY BARRIER DIODE CHIPS

# **DESCRIPTION**

- Ø 2SB267100MA is a schottky barrier diode chips fabricated in silicon epitaxial planar technology;
- $\ensuremath{{\varnothing}}$  Due to special schottky barrier structure, the chips have very low reverse leakage current ( typical  $I_R{=}0.002 mA@Vr{=}100V$  ) and maximum 150°C operation junction temperature;
- Ø Low power losses, high efficiency;
- Ø Guard ring construction for transient protection;
- Ø High ESD capability;
- Ø High surge capability;
- Ø Packaged products are widely used in switching power suppliers, polarity protection circuits and other electronic circuits;
- Ø Chip Size: 2670μm X 2670μm;
- Ø Chip Thickness: 280±20μm;
- Ø Have two top side electrode materials for customer to choose, detail refer to ordering specifications.



Chip Topography and Dimensions

La: Chip Size: 2670µm; Lb: Pad Size: 2470µm;

### **ORDERING SPECIFICATIONS**

Product Name	Specification		
2SB267100MAYY	For Axial leads package		
2SB267100MAYL	For Au and AISi wire bonding		
	package		

#### ABSOLUTE MAXIMUM RATINGS

Parameters	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage	VRRM	100	V
Average Forward Rectified Current	IFAV 10		Α
Peak Forward Surge Current@8.3ms	IFSM	150	Α
Maximum Operation Junction Temperature	TJ	150	°C
Storage Temperature Range	Tstg	-40~150	°C

## ELECTRICAL CHARACTERISTICS (Tamb=25°C)

Parameters	Symbol	Test Conditions	Min.	Max.	Unit
Reverse Voltage	VBR	IR=0.5mA	100		V
Forward Voltage	VF	IF=10A		0.85	V
Reverse Current	lR	VR=100V		0.5	mA